

Claims 8 - 17 and 21 - 26 are rejected under 35 USC § 103(a) as being unpatentable over U.S. Patent No. 4,985,750, to Hoshino, in view of Landers et al.

Claims 18 - 20 are rejected under 35 USC § 103(a) as being unpatentable over Gelatos et al., in combination with Landers et al., as applied to Claims 8 - 17, and further in view of U.S. Patent No. 5,707,498, to Ngan.

Claims 18 - 20 and 27 are rejected under 35 USC § 103(a) as being unpatentable over Hoshino, in view of Landers et al., as applied to Claims 8 - 17, and further in view of Ngan.

Please amend the application as follows:

IN THE SPECIFICATION:

Page 4, line 24, please delete "Application Serial No. 08/924,487" and insert

-- No. 5,882,399 --;

line 25, please delete "filed August 23, 1997 (Docket No. 1987)" and insert -- issued

March 16, 1999 --.

IN THE CLAIMS:

Please amend Claims 12 and 27 as follows.

*Claims not being amended are presented in italics for reference purposes only.*

8. *A method of producing a combined barrier layer and wetting layer structure which is used in combination with a conductive layer, said method comprising the steps of:*

a) *depositing a first layer of TaN<sub>x</sub> having a thickness ranging from greater than about 10 Å to about 1,000 Å;*

b) *depositing a second layer of Ta having a thickness ranging from about 5 Å to about 500 Å; and*